



## Material Content Data Sheet



<b>Sales Product Name</b>		IPS80R1K2P7		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001662416						
<b>Package</b>		PG-TO251-3-344		<b>Weight*</b>		334.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.552	0.46	0.46	4645	4645
leadframe	inorganic material	phosphorus	7723-14-0	0.046	0.01		139	
	non noble metal	iron	7439-89-6	0.154	0.05		462	
wire	non noble metal	copper	7440-50-8	154.154	46.14	46.20	461244	461845
	non noble metal	aluminium	7429-90-5	0.469	0.14	0.14	1403	1403
encapsulation	organic material	carbon black	1333-86-4	0.445	0.13		1332	
	plastics	epoxy resin	-	13.508	4.04		40416	
leadfinish	inorganic material	silicondioxide	60676-86-0	134.482	40.24	44.41	402382	444130
	non noble metal	tin	7440-31-5	4.142	1.24	1.24	12394	12394
plating	non noble metal	nickel	7440-02-0	0.607	0.18	0.18	1815	1815
solder	non noble metal	tin	7440-31-5	0.035	0.01		105	
	noble metal	silver	7440-22-4	0.044	0.01		131	
heatspreader	non noble metal	lead	7439-92-1	1.679	0.50	0.52	5022	5258
	inorganic material	phosphorus	7723-14-0	0.007	0.00		21	
	non noble metal	iron	7439-89-6	0.023	0.01		69	
	non noble metal	copper	7440-50-8	22.867	6.84	6.85	68420	68510
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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